

# CD4013B Types

## CMOS Dual 'D'-Type Flip-Flop

High-Voltage Types (20-Volt Rating)

■ CD4013B consists of two identical, independent data-type flip-flops. Each flip-flop has independent data, set, reset, and clock inputs and Q and  $\bar{Q}$  outputs. These devices can be used for shift register applications, and, by connecting  $\bar{Q}$  output to the data input, for counter and toggle applications. The logic level present at the D input is transferred to the Q output during the positive-going transition of the clock pulse. Setting or resetting is independent of the clock and is accomplished by a high level on the set or reset line, respectively.

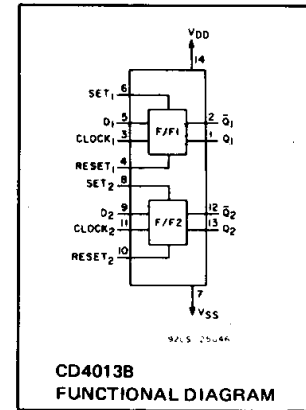
The CD4013B types are supplied in 14-lead hermetic dual-in-line ceramic packages (F3A suffix), 14-lead dual-in-line plastic packages (E suffix), 14-lead small-outline packages (M, MT, M96, and NSR suffixes), and 14-lead thin shrink small-outline packages (PW and PWR suffixes).

### Features:

- Set-Reset capability
- Static flip-flop operation — retains state indefinitely with clock level either "high" or "low"
- Medium-speed operation — 16 MHz (typ.) clock toggle rate at 10V
- Standardized symmetrical output characteristics
- 100% tested for quiescent current at 20 V
- Maximum input current of 1  $\mu$ A at 18 V over full package temperature range; 100 nA at 18 V and 25°C
- Noise margin (over full package temperature range): 1 V at  $V_{DD}=5$  V  
2 V at  $V_{DD}=10$  V  
2.5 V at  $V_{DD}=15$  V
- 5-V, 10-V, and 15-V parametric ratings
- Meets all requirements of JEDEC Tentative Standard No. 13B, "Standard Specifications for Description of 'B' Series CMOS Devices"

### Applications:

- Registers, counters, control circuits



### RECOMMENDED OPERATING CONDITIONS

At  $T_A = 25^\circ\text{C}$ , Except as Noted. For maximum reliability, nominal operating conditions should be selected so that operation is always within the following ranges:

CHARACTERISTIC	$V_{DD}$ (V)	LIMITS		UNITS
		MIN.	MAX.	
Supply-Voltage Range (For $T_A =$ Full Package Temperature Range)	—	3	18	V
Data Setup Time $t_S$	5	40	—	ns
	10	20	—	
Clock Pulse Width $t_W$	15	15	—	ns
	5	140	—	
Clock Input Frequency $f_{CL}$	10	60	—	ns
	15	40	—	
Clock Rise or Fall Time $t_{rCL}$ , $t_{fCL}$	5	—	3.5	MHz
	10	—	8	
Set or Reset Pulse Width $t_W$	15	—	12	MHz
	5	—	15	
Set or Reset Pulse Width $t_W$	10	—	10	$\mu$ s
	15	—	5	
Set or Reset Pulse Width $t_W$	5	180	—	ns
	10	80	—	
	15	50	—	

\*If more than one unit is cascaded in a parallel clocked operation,  $t_{rCL}$  should be made less than or equal to the sum of the fixed propagation delay time at 15 pF and the transition time of the output driving stage for the estimated capacitive load.

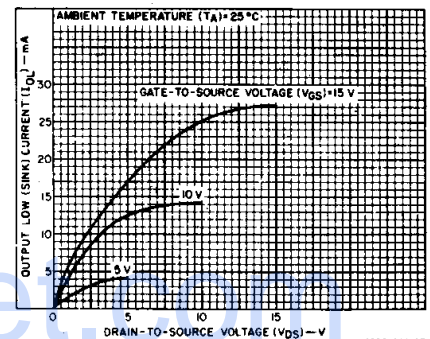


Fig. 1 — Typical output low (sink) current characteristics.

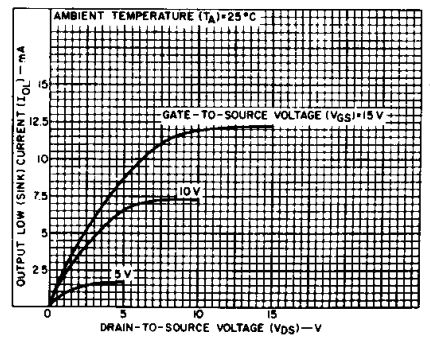


Fig. 2 — Minimum output low (sink) current characteristics.

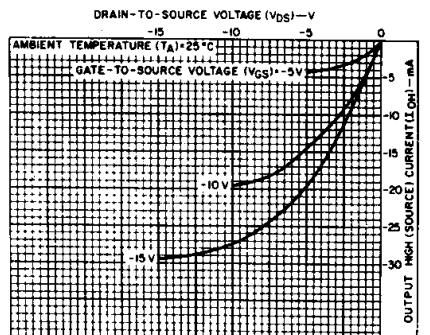


Fig. 3 — Typical output high (source) current characteristics.

# CD4013B Types

## STATIC ELECTRICAL CHARACTERISTICS

CHARACTERISTIC	CONDITIONS			LIMITS AT INDICATED TEMPERATURES (°C)							UNITS
	V <sub>O</sub> (V)	V <sub>IN</sub> (V)	V <sub>DD</sub> (V)	-55	-40	+85	+125	+25			
								Min.	Typ.	Max.	
Quiescent Device Current I <sub>DD</sub> Max.	—	0.5	5	1	1	30	30	—	0.02	1	μA
	—	0.10	10	2	2	60	60	—	0.02	2	
	—	0.15	15	4	4	120	120	—	0.02	4	
Output Low (Sink) Current, I <sub>OL</sub> Min.	0.4	0.5	5	0.64	0.61	0.42	0.36	0.51	1	—	mA
	0.5	0.10	10	1.6	1.5	1.1	0.9	1.3	2.6	—	
	1.5	0.15	15	4.2	4	2.8	2.4	3.4	6.8	—	
Output High (Source) Current, I <sub>OH</sub> Min.	4.6	0.5	5	-0.64	-0.61	-0.42	-0.36	-0.51	-1	—	mA
	2.5	0.5	5	-2	-1.8	-1.3	-1.15	-1.6	-3.2	—	
	9.5	0.10	10	-1.6	-1.5	-1.1	-0.9	-1.3	-2.6	—	
Output Voltage: Low-Level, V <sub>OL</sub> Max.	—	0.5	5	0.05				—	0	0.05	V
	—	0.10	10	0.05				—	0	0.05	
	—	0.15	15	0.05				—	0	0.05	
Output Voltage: High-Level, V <sub>OH</sub> Min.	—	0.5	5	4.95				4.95	5	—	V
	—	0.10	10	9.95				9.95	10	—	
	—	0.15	15	14.95				14.95	15	—	
Input Low Voltage, V <sub>IL</sub> Max.	0.5, 4.5	—	5	1.5				—	—	1.5	V
	1.9	—	10	3				—	—	3	
	1.5, 13.5	—	15	4				—	—	4	
Input High Voltage, V <sub>IH</sub> Min.	0.5, 4.5	—	5	3.5				3.5	—	—	V
	1.9	—	10	7				7	—	—	
	1.5, 13.5	—	15	11				11	—	—	
Input Current, I <sub>IN</sub> Max.	—	0.18	18	±0.1	±0.1	±1	±1	—	±10 <sup>-5</sup>	±0.1	μA

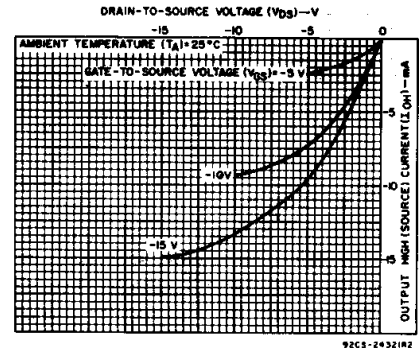


Fig. 4 — Minimum output high (source) current characteristics.

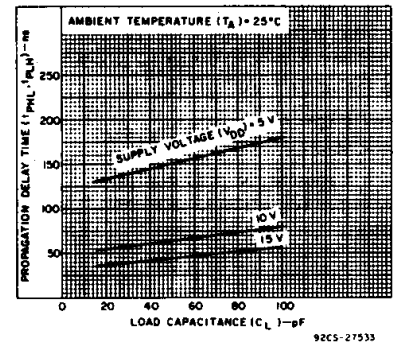


Fig. 5 — Typical propagation delay time vs. load capacitance (CLOCK or SET to Q, CLOCK or RESET to Q).

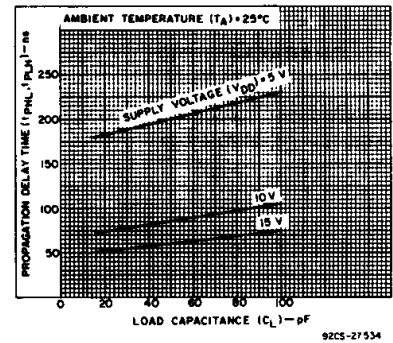


Fig. 6 — Typical propagation delay time vs. load capacitance (SET to Q or RESET to Q).

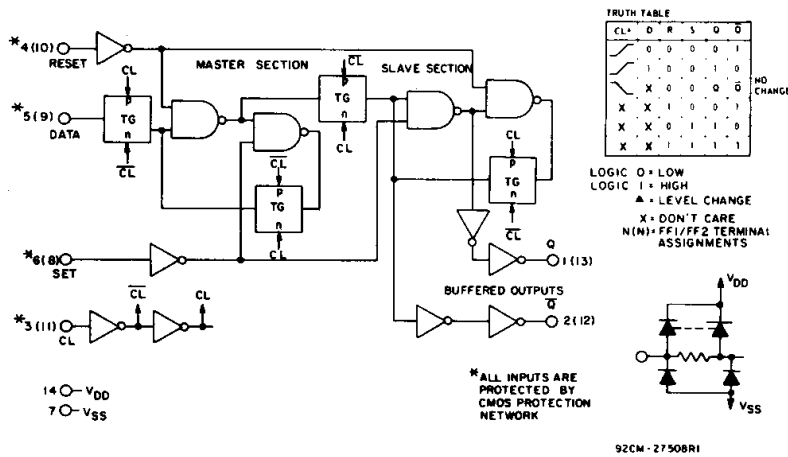


Fig. 7 — Logic diagram and truth table for CD4013B (one of two identical flip-flops).

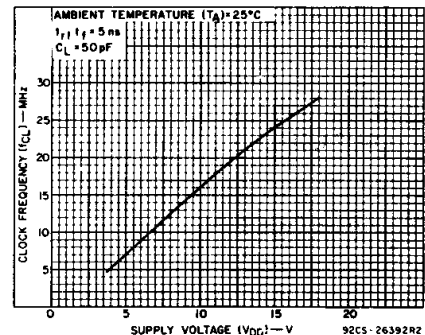


Fig. 8 — Typical maximum clock frequency vs. supply voltage.

# CD4013B Types

## MAXIMUM RATINGS, Absolute-Maximum Values:

### DC SUPPLY-VOLTAGE RANGE, (V<sub>DD</sub>)

Voltages referenced to V<sub>SS</sub> Terminal ..... -0.5V to +20V

INPUT VOLTAGE RANGE, ALL INPUTS ..... -0.5V to V<sub>DD</sub> +0.5V

DC INPUT CURRENT, ANY ONE INPUT ..... ±10mA

### POWER DISSIPATION PER PACKAGE (P<sub>D</sub>):

For T<sub>A</sub> = -55°C to +100°C ..... 500mW

For T<sub>A</sub> = +100°C to +125°C ..... Derate Linearly at 12mW/°C to 200mW

### DEVICE DISSIPATION PER OUTPUT TRANSISTOR

FOR T<sub>A</sub> = FULL PACKAGE-TEMPERATURE RANGE (All Package Types) ..... 100mW

OPERATING-TEMPERATURE RANGE (T<sub>A</sub>) ..... -55°C to +125°C

STORAGE TEMPERATURE RANGE (T<sub>stg</sub>) ..... -65°C to +150°C

### LEAD TEMPERATURE (DURING SOLDERING):

At distance 1/16 ± 1/32 inch (1.59 ± 0.79mm) from case for 10s max ..... +265°C

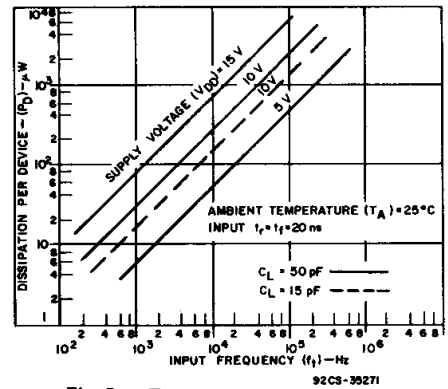


Fig. 9 – Typical power dissipation vs. frequency.

## DYNAMIC ELECTRICAL CHARACTERISTICS

At T<sub>A</sub> = 25°C; Input t<sub>r</sub>, t<sub>f</sub> = 20 ns, C<sub>L</sub> = 50 pF, R<sub>L</sub> = 20 kΩ

CHARACTERISTIC	TEST CONDITIONS V <sub>DD</sub> (V)	LIMITS			UNITS
		MIN.	TYP.	MAX.	
Propagation Delay Time: Clock to Q or $\bar{Q}$ Outputs t <sub>PHL</sub> , t <sub>PLH</sub>	5	—	150	300	ns
	10	—	65	130	
	15	—	45	90	
Set to Q or Reset to $\bar{Q}$ t <sub>PLH</sub>	5	—	150	300	ns
	10	—	65	130	
	15	—	45	90	
Set to $\bar{Q}$ or Reset to Q t <sub>PHL</sub>	5	—	200	400	ns
	10	—	85	170	
	15	—	60	120	
Transition Time t <sub>THL</sub> , t <sub>TLH</sub>	5	—	100	200	ns
	10	—	50	100	
	15	—	40	80	
Maximum Clock Input Frequency# f <sub>CL</sub>	5	3.5	7	—	MHz
	10	8	16	—	
	15	12	24	—	
Minimum Clock Pulse Width t <sub>w</sub>	5	—	70	140	ns
	10	—	30	60	
	15	—	20	40	
Minimum Set or Reset Pulse Width t <sub>w</sub>	5	—	90	180	ns
	10	—	40	80	
	15	—	25	50	
Minimum Data Setup Time t <sub>s</sub>	5	—	20	40	ns
	10	—	10	20	
	15	—	7	15	
Minimum Data Hold Time t <sub>h</sub>	5	—	2	5	ns
	10	—	2	5	
	15	—	2	5	
Clock Input Rise or Fall Time t <sub>rCL</sub> , t <sub>fCL</sub>	5	—	—	15	μs
	10	—	—	10	
	15	—	—	5	
Input Capacitance C <sub>IN</sub>	Any Input	—	5	7.5	pF

#Input t<sub>r</sub>, t<sub>f</sub> = 5 ns.

## TEST CIRCUITS

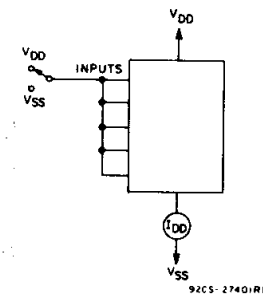


Fig. 10 – Quiescent device current.

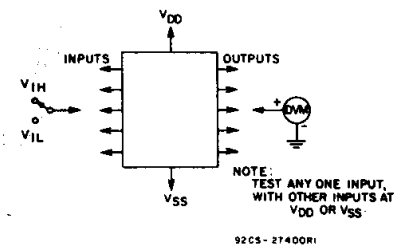


Fig. 11 – Input voltage.

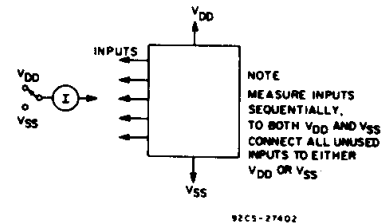


Fig. 12 – Input current.

## CD4013B Types

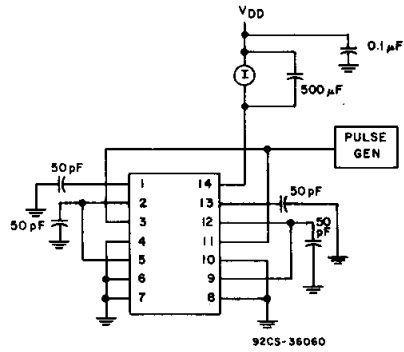
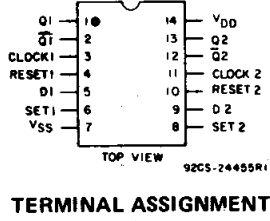
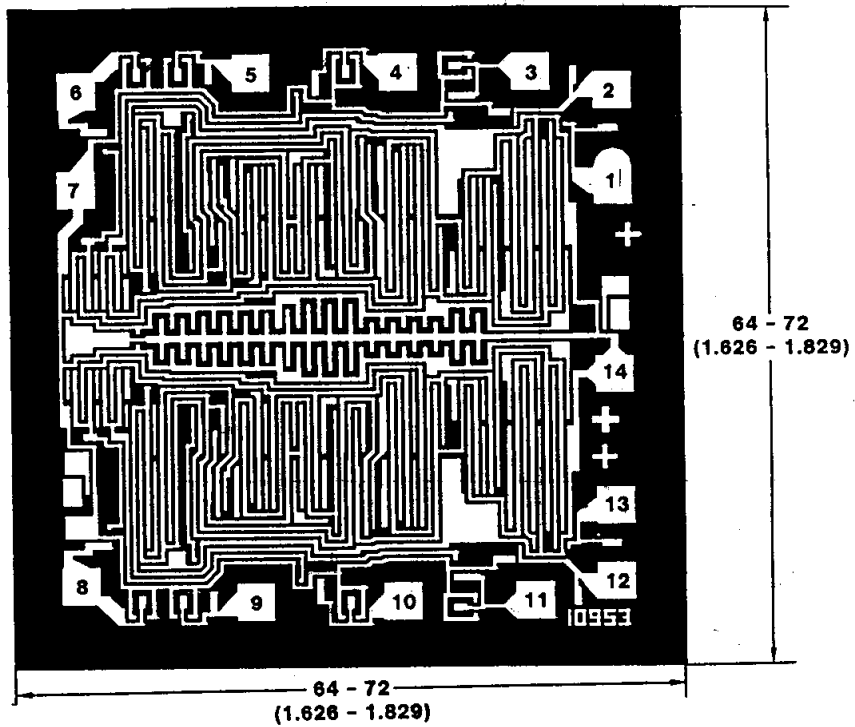


Fig. 13—Dynamic power dissipation test circuit.

### DIMENSIONS AND PAD LAYOUT FOR CD4013BH



*Dimensions in parentheses are in millimeters and are derived from the basic inch dimensions as indicated. Grid graduations are in mils ( $10^{-3}$  inch).*

**PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/ Ball Finish	MSL Peak Temp <sup>(3)</sup>	Samples (Requires Login)
89267AKB3T	OBSOLETE	CFP	WR	14		TBD	Call TI	Call TI	
CD4013BE	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
CD4013BEE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
CD4013BF	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	
CD4013BF3A	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	
CD4013BF3AS2534	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI	
CD4013BK3	OBSOLETE	CFP	WR	14		TBD	Call TI	Call TI	
CD4013BM	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD4013BM96	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD4013BM96E4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD4013BM96G4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD4013BME4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD4013BMG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD4013BMT	ACTIVE	SOIC	D	14	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD4013BMTE4	ACTIVE	SOIC	D	14	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD4013BMTG4	ACTIVE	SOIC	D	14	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD4013BNSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD4013BNSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD4013BNSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD4013BPW	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/ Ball Finish	MSL Peak Temp <sup>(3)</sup>	Samples (Requires Login)
CD4013BPWE4	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD4013BPWG4	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD4013BPWR	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD4013BPWRE4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD4013BPWRG4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
JM38510/05151BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	
M38510/05151BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSELETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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**OTHER QUALIFIED VERSIONS OF CD4013B, CD4013B-MIL :**

- Catalog: [CD4013B](#)
- Military: [CD4013B-MIL](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications

**TAPE AND REEL INFORMATION**
**REEL DIMENSIONS**

**TAPE DIMENSIONS**


A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

**TAPE AND REEL INFORMATION**

\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CD4013BM96	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
CD4013BM96G4	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
CD4013BMT	SOIC	D	14	250	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
CD4013BNSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
CD4013BPWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1



## TAPE AND REEL BOX DIMENSIONS



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CD4013BM96	SOIC	D	14	2500	367.0	367.0	38.0
CD4013BM96G4	SOIC	D	14	2500	367.0	367.0	38.0
CD4013BMT	SOIC	D	14	250	367.0	367.0	38.0
CD4013BNSR	SO	NS	14	2000	367.0	367.0	38.0
CD4013BPWR	TSSOP	PW	14	2000	367.0	367.0	35.0

J (R-GDIP-T\*\*)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package is hermetically sealed with a ceramic lid using glass frit.
  - D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
  - E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

N (R-PDIP-T\*\*)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  -  Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
  -  The 20 pin end lead shoulder width is a vendor option, either half or full width.

D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  -  Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
  -  Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
  - E. Reference JEDEC MS-012 variation AB.

D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Publication IPC-7351 is recommended for alternate designs.
  - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
  - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

PW (R-PDSO-G14)

PLASTIC SMALL OUTLINE

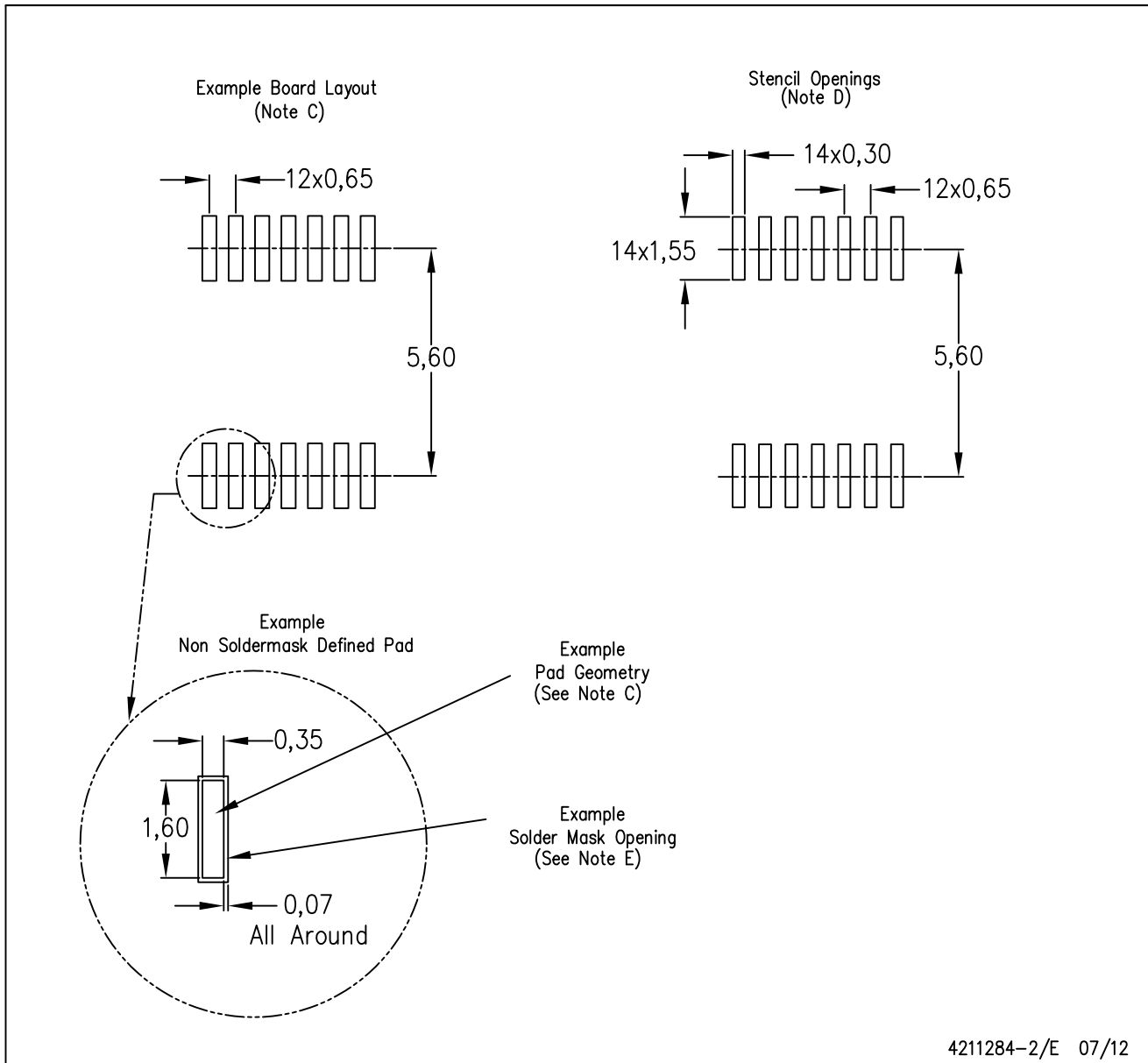


4040064-3/G 02/11

- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
  - B. This drawing is subject to change without notice.
  - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
  - D. Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
  - E. Falls within JEDEC MO-153

PW (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- NOTES:
- All linear dimensions are in millimeters.
  - This drawing is subject to change without notice.
  - Publication IPC-7351 is recommended for alternate designs.
  - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
  - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

# MECHANICAL DATA

NS (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



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